

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
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EPAS ID: PAT3155257

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	SHANG-CHUN CHEN	12/15/2014
	CHA-HSIN LIN	12/15/2014
	YU-CHEN HSIN	12/15/2014
RECEIVING PARTY DATA		
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Property Type	Number	
Application Number:	14574348	
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NAME OF SUBMITTER:	BELINDA LEE	
SIGNATURE:	/Belinda Lee/	
DATE SIGNED:	12/18/2014	
Total Attachments: 2		
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ASSIGNMENT

WHEREAS,

1. Shang-Chun Chen
3. Yu-Chen Hsin

2. Cha-Hsin Lin

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF**

☐ Filed:

Serial No.

☒ Executed concurrently with the execution of this instrument

WHEREAS 1. Industrial Technology Research Institute
of No. 195, Sec. 4, Chung Hsing Rd., Chutung, Hsinchu 31040, Taiwan, R.
O. C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

P51010167USC1
45488-US-PA-0P

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: 陳尚駿 Shang-Chun Chen Date: 2014.12.15
Sole or First Joint Inventor: Shang-Chun Chen

Signature: 林哲宏 CHA-HSIN LIN Date: 2014.12.15
Second Joint Inventor (if any): Cha-Hsin Lin

Signature: 許毓真 Yu-Chen Hsin Date: 2014.12.15
Third Joint Inventor (if any): Yu-Chen Hsin